IPC - ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information			
upplier Inforn	nation														
Company name*			Company unique ID			Į	Unique ID Authority					Response Date*			
nsemi												2025-05-11			
Contact Name		Title	Title - Contact			F	Phone - Contact*					Email - Contact*			
Product-Env-Stewa	ards	Prod	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com			
uthorized Represe	entative*	Title	Title - Representative			F	Phone - Representative*					Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com			
Requesto	Requester Item Number Mfr Ite		Item Number Mfr Item Name				Effective Date	Versio	on	Manufacturing Site		W	eight*	UOM	Unit Type
		AFGHL75T65SQDC 650V 75A FS4 Hy		650V 75A FS4 Hyt	brid IGBT		2025-05-11 CPA			54	156.725	mg	Each		
	Process Information		1 D A1	J	CTD 020 MCI	D-4i	Deals Dece	D - d-	T	Mary Tile	Darle 5	T	N. N. N.	a of Doflana Cou	1
8 - 1 - 1			Terminal Base Alloy J-S' CU Allov NA		STD-020 MSL	Rating		Process Body Temperature Max Time at Pea		ne at Peak			er of Reflow Cyc	eles	
	n (Sn) - annealed	CU All	lloy	N	A		0		IC.	30		second	s 3		
omments															
For more informati	on regarding material co	omposition please	se refer to j	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier has not independently verified information provided by others, Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon Carbide	409-21-2		32	mg
			Supplier	Silicon (Si)	7440-21-3		0	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			A	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg	Supplier	Brominated Epoxy Resin-2	68541-56-0		43.495	mg
_			Supplier	Other Epoxy resins	Proprietary Data		52.194	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.796	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1513.6261	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		86.99	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg